

Notice of References Cited	Application/Control No. 10/765,931		Applicant(s)/Patent Under Reexamination KUKIMOTO ET AL.	
	Examiner Khiem D. Nguyen		Art Unit 2823	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,923,875	08-2005	Ikeda et al.	148/24
*	B	US-6,784,087	08-2004	Lee et al.	438/612
*	C	US-6,586,322	07-2003	Chiu et al.	438/612
*	D	US-6,408,511	06-2002	Branchevsky, Shaul	29/843
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	L	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Patent Abstract of Japan "Method for forming bump" Publication number 2002-334895, Sakuyama Seiki (22.11.2002), translation.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.